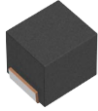


SMD POWER INDUCTOR

FNLV series (Rev. 5.0)



Features

- * RoHS compliant
- * Lead-free materials is used for the plating on the terminals
- * Use metal terminals that realize excellent connection.
- * Good heat durability that withstands lead-free reflow.
- * High resistance to heat, humidity, mechanical shocks and presser. Accurate dimensions for automatically surfacemounted

Product Identification

FNLV 25 - 8R2 J
1 2 3 4

1. Product Code
2. Size Code
3. Inductance: 8.2uH
4. Tolerance: J=±5%

Applications

- * Mobile device
- * Handheld device
- * Low-profile device
- * Panel...

Operating & Storage Condition :

- * Operating Temp. : -40 to +105 °C
- * Storage Temp. : -40 to +85 °C
- * Storage Life Time : 12 Months @25 °C , RH 65%

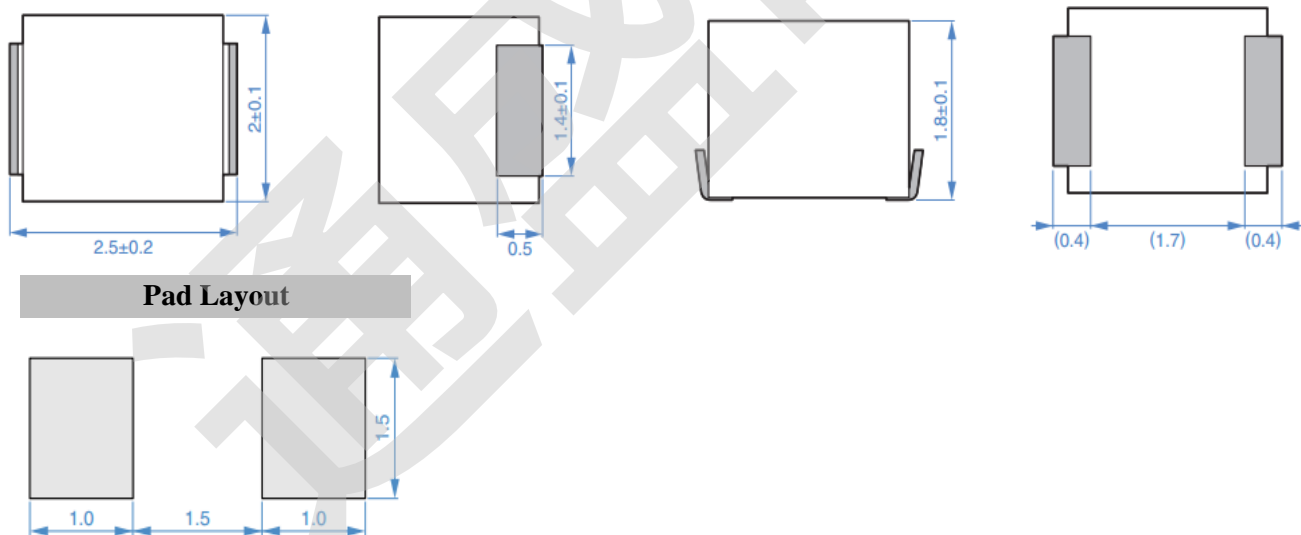
Test Equipment :

- * HP4284A, HP42841A- L, IDC, Q, RDC
- * HP8753D NETWORK ANALYZER- SRF

Standard Atmospheric Conditions :

- * Ambient Temp : 20+/-5 °C
- * Relative Humidity : 75+/-10%

Dimension & Recommended PAD Layout: [mm]



Electrical Characteristics

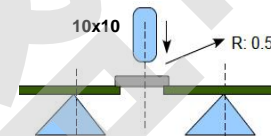
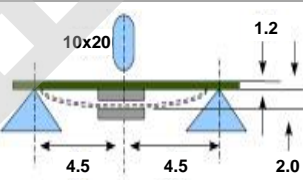
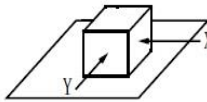
| P/N | Inductance (uH) | Q | SRF (MHz) | DCR (Ω) | IDC (mA) |
|-------------|-----------------|---------|-----------|-----------|----------|
| FNLV25-8R2J | 8.2 ±5% | 25 min. | 36 min. | 3.05 max. | 160 max. |

* Test frequency: @7.96MHz

* IDC : This indicates the value of current when the inductance is 10% lower than its initial value at D.C. superposition or D.C. current when at ΔT=40°C, whichever is lower. (Ta=20°C)

RELIABILITY TEST

SMD Type :

| SN | Test Item | Test Method | Standard | Samples (pcs) | | | | | | | | | | | | |
|------------------|--|--|---|---|------|------------------|--------------|-----------|------------------|--------------|-----------|------------------|--------------|-----------|--|----|
| 1 | Thermal Shock 冷热冲击测试 | Temperature: - 40 °C / +85 °C kept stabilized for 30 minutes ; Cycle: 100 cycles (power off) | No appearance deformation Inductance deviation within $\pm 5\%$ | 30 | | | | | | | | | | | | |
| 2 | Humidity Resistance 防潮性能测试 | Humidity: 90%- 95% RH; Temperature: 40 ± 2 °C Time: 500 ± 12 hours | No appearance deformation Inductance deviation within $\pm 5\%$ | 30 | | | | | | | | | | | | |
| 3 | High Temperature 耐热测试 | Temperature: 105 ± 2 °C Time: 500 ± 12 Hours | No appearance deformation Inductance deviation within $\pm 5\%$ | 30 | | | | | | | | | | | | |
| 4 | Low Temperature 耐寒测试 | Temperature: - 40 ± 2 °C Time: 500 ± 12 Hours | No appearance deformation Inductance deviation within $\pm 5\%$ | 30 | | | | | | | | | | | | |
| 5 | Temperature and Humidity Cycle 温/湿度循环测试 | <table border="0"> <tr> <td>Temperature</td> <td>Humidity</td> <td>Time</td> </tr> <tr> <td>25 °C ± 2 °C</td> <td>90% - 95% RH</td> <td>3.0 hours</td> </tr> <tr> <td>55 °C ± 2 °C</td> <td>95% - 96% RH</td> <td>5.0 hours</td> </tr> <tr> <td>25 °C ± 2 °C</td> <td>90% - 95% RH</td> <td>3.0 hours</td> </tr> </table> Cycle: 100 cycles | Temperature | Humidity | Time | 25 °C ± 2 °C | 90% - 95% RH | 3.0 hours | 55 °C ± 2 °C | 95% - 96% RH | 5.0 hours | 25 °C ± 2 °C | 90% - 95% RH | 3.0 hours | No appearance deformation Inductance deviation within $\pm 5\%$ | 30 |
| Temperature | Humidity | Time | | | | | | | | | | | | | | |
| 25 °C ± 2 °C | 90% - 95% RH | 3.0 hours | | | | | | | | | | | | | | |
| 55 °C ± 2 °C | 95% - 96% RH | 5.0 hours | | | | | | | | | | | | | | |
| 25 °C ± 2 °C | 90% - 95% RH | 3.0 hours | | | | | | | | | | | | | | |
| 6 | Reflow Heating Resistance 回流焊耐热性测试 | IR-Reflow (3 times) Preheat: 150~200 °C Time: 60-120 sec. Peak Temp.: 255 ± 5 °C Time: 30 sec. Reflow Temp.: above 217 °C Time: 60-150 sec. | No appearance deformation Inductance deviation within $\pm 5\%$ | 30 | | | | | | | | | | | | |
| 7 | Iron Heating Resistance 烙铁焊耐热性测试 | Soldering Temp.: 350 ± 5 °C Time: 3 ± 1 sec. | No appearance deformation Inductance deviation within $\pm 5\%$ | 30 | | | | | | | | | | | | |
| 8 | Withstanding Voltage 耐压测试 | 100 VDC/ 1 minute, between core & winding | No dielectric breakdown | 30 | | | | | | | | | | | | |
| 9 | Rated Current 额定电流测试 | Temperature: 25 ± 3 °C; Time: 10 minutes Load: Rated Current | Inductance and Temp. Rise variation within spec. | 30 | | | | | | | | | | | | |
| 10 | Bending Strength 折断力测试 | Uint: mm IR-Reflow (2 times) Force : 1 kgf/ min. |  | No appearance deformation Inductance deviation within $\pm 3\%$ | 30 | | | | | | | | | | | |
| 11 | Flexure Strength 抗弯强度测试 | Uint: mm IR-Reflow (2 times) Solder cream 0.15mm |  | No appearance deformation Inductance deviation within $\pm 3\%$ | 30 | | | | | | | | | | | |
| 12 | Electrode Strength 电极强度测试 | Mounted on PCB Pushed in X, Y direction, Strength: 5N for 10 ± 2 sec. |  | No electrode detachment No appearance deformation Inductance deviation within $\pm 3\%$ | 30 | | | | | | | | | | | |
| 13 | Vibration 振动测试 | Frequency: 10Hz-55Hz Amplitude: 1.5mm Direction: X,Y,Z Time: 2 hours for each Product: after packing | No appearance deformation Inductance deviation within $\pm 3\%$ | 30 | | | | | | | | | | | | |
| 14 | Dropping 跌落测试 | Freely dropped down; Height: 1m ; Direction: 1 Angle ridge; 3 surfaces; Product: after packing | No appearance deformation Inductance deviation within $\pm 3\%$ | 30 | | | | | | | | | | | | |

Remark: Before/after reliability test for above each item, must carry out visual inspection and/or measure crucial dimension inspection if needed. If confirmation of defects is required, use visual aids or equipment such as 10X magnifying glass, microscope etc. to check.

RECOMMENDATION

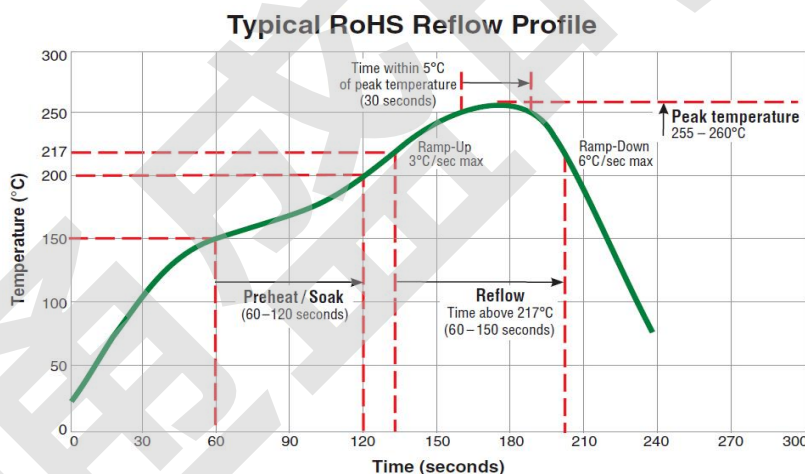
General

- ◆ Products should not be kept in unsuitable storage conditions, such as areas susceptible to high temperatures, high humidity, dust or corrosion.
- ◆ Don't use products in a place where dew condenses. Since dew condensation caused by temperature change, please pay special attention when using products in a sealed condition.
- ◆ Always handle products with care.
- ◆ Don't touch electrodes directly with bare hands as oil secretions may inhibit soldering.
- ◆ Always ensure optimum conditions for soldering.
- ◆ Don't bend the terminals or subject them to excessive stress.
- ◆ Please ensure that all terminals and case lugs are completely fixed with solder onto PCB.
- ◆ Avoid placing chip inductors near the edge of the PCB.
- ◆ Our SMD coils are designed for automatic mounting. Please be careful if soldering by hand.
- ◆ Don't touch any exposed winding part and avoid coming into contact with the guide of electrode in automatic mounting.
- ◆ Our specification limits the quality of the component as a single unit. Please ensure the component is thoroughly evaluated in your application circuit.
- ◆ When using our high voltage inverter transformers, please keep 2mm away from the electric conductor.

Soldering

◆ Reflow soldering

Please refer to the following recommended condition. Please do not add any stress to a product until it returns in normal temperature after reflow soldering.



◆ Lead free soldering

When using products with lead free soldering, we request to use them after confirming of adhesion, temperature of resistance to soldering heat, soldering etc. sufficiently.

◆ Soldering iron

Put the soldering iron on the land-pattern.

Soldering iron's temperature - Below 350 °C (FCD43 Type).

Duration - 3 seconds or less

The soldering iron should not directly touch the inductor.

RECOMMENDATION

Cleaning

- ◆ Refrain from cleaning coils. Ultrasonic cleaning may cause broken products. If it is a must, kindly refer to following advice or consult with our company.
 - ◆ When cleaning the PC board after the inductors are all mounted, select the appropriate cleaning solution according to the type of flux used and purpose of the cleaning (e.g. to remove soldering flux or other materials from the production process.)
 - ◆ Cleaning conditions should be determined after verifying through a test run, the cleaning process does not affect the inductor's characteristics.
 - ◆ The use of inappropriate solutions can cause foreign substances such as flux residue to adhere to the inductor, resulting in a degradation of the inductor's electrical properties, especially insulation resistance.
 - ◆ Inappropriate cleaning conditions (insufficient or excessive cleaning) may detrimentally affect the performance of the inductors.
 - * In the case of ultrasonic cleaning, too much power output can cause excessive vibration of the PC board which may lead to the cracking of the inductor or the soldered portion, or decrease the terminal electrodes' strength. Thus following conditions shall be checked.
 - Ultrasonic output below 20W
 - Ultrasonic frequency below 40KHz
 - Ultrasonic washing period 5 minutes or less

Handling

- ◆ Keep the product away from all magnets and magnetic objects.
- ◆ Breakaway PC boards (splitting along perforations)
 1. When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or twisting to the board.
 2. Board separation should not be done manually, but by using the appropriate devices.
- ◆ Mechanical considerations
 - Please do not give the product any excessive mechanical shocks and power in transportation.
- ◆ Pick-up pressure
 - Damage and a characteristic can vary with an excessive shock or stress. Please don't push to add any pressure to a winding part.
- ◆ Packing- Please avoid accumulation of a packing box as much as possible.

Storage

- ◆ To maintain the solderability of terminal electrodes and to keep the packaging material in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible.
- ◆ Recommended conditions
 - Ambient temperature Below 40°C
 - Humidity Below 70% RH
- ◆ The ambient temperature must be kept below 40°C. Even under ideal storage conditions inductor electrode solderability decreases as time passes, so inductors should be used within 6 months from the time of delivery.
- ◆ In case of storage over 6 months, solderability shall be checked before actual usage.
- ◆ The packaging material should be kept where no chlorine or sulfur exists in the air.
- ◆ Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/ packaging materials may take place.